

REMARKS

This application pertains to a novel method for bonding electrical modules to card bodies.

Claims 2-6 and 8 are pending, claims 1 and 7 being cancelled by this amendment.

The pending claims have been amended to limit their scope to the method of original claim 5, which has now been made the main independent claim.

Claim 4 stands rejected under 35 U.S.C. 112, second paragraph, because the Examiner views the "reactive" resins of claim 4 as contradicting claim 1, as it is unclear to the Examiner how reactive resins like those of claim 4 can be incorporated into the adhesive and still let the adhesive be truly thermoplastic.

Those skilled in the art understand that in principle it is possible to have a thermoplastic adhesive comprising reactive resins, even after reaction. Whether the system becomes hard or remains thermoplastic will depend on the polymer, the reactive resin and the amount of both in the mixture. Nevertheless, Applicants' adhesive system would be expected to become fully cured after heating.

The rejection of claim 4 under 35 U.S.C. 112, second paragraph, should therefore now be withdrawn.

Claims 1, 3 and 7 stand rejected under 35 U.S.C. 102(c) as anticipated by Copperwheat (U.S. 6,846,759). Claims 1 and 7 have been cancelled, so that claim 3 is the only claim remaining subject to this rejection. Claim 5 is not included in this rejection, and claim 3 has been amended to a method claim depending from claim 5.

Claim 3, as amended, pertains to a method of bonding chip modules in card bodies. Copperwheat pertains to the application of an adhesive to the surface of a felt cloth. Nothing in Copperwheat could possibly lead to Applicants' method for bonding chip modules in card bodies.

Accordingly, the rejection of claims 1, 3 and 7 under 35 U.S.C. 102(c) as anticipated by Copperwheat (U.S. 6,846,759) should now be withdrawn.

Claims 2, 5, 6 and 8 stand rejected under 35 U.S.C. 103(a) as obvious over Copperwheat (U.S. 6,846,759), as applied to claim 1 above, and in view of Watada (U.S. 6,012,64).

Applicants' claims pertain to a method for bonding chip modules in card bodies.

Copperwheat's adhesive is used on felt, not on a card or a chip module, and there is nothing in Copperwheat that would teach or suggest anything about bonding chip modules in card bodies.

Watada discloses a polyester card having a cavity for embedding a chip module, but there is nothing in either Watada or Copperwheat that would suggest that the adhesive of Copperwheat could be used to bond a chip module into a card body.

No combination of Copperwheat and Watada could possibly lead to Applicants' novel method of bonding chip modules in card bodies, and the rejection of claims 2, 5, 6 and 8 under 35 U.S.C. 103(a) as obvious over Copperwheat (U.S. 6,846,759), as applied to claim 1 above, and in view of Watada (U.S. 6,012,64) should now be withdrawn.

Claim 4 stands rejected under 35 U.S.C. 103(a) as obvious over Copperwheat (U.S. 6,846,759) as applied to claim 1 above and further in view of Uno (U.S. 4,065,439). The Examiner finds it obvious to include an epoxy in the hot melt adhesive of Copperwheat.

However, Applicants' claim 4 has now been amended to recite a method for bonding chip modules in card bodies, and there is absolutely nothing to be found anywhere in either Copperwheat or Uno that would teach or suggest anything about bonding chip modules in card bodies. Accordingly, the rejection of claim 4 under 35 U.S.C. 103(a) as obvious over Copperwheat (U.S. 6,846,759) as applied to claim 1 above and further in view of Uno (U.S. 4,065,439) should now be withdrawn.

In view of the present amendments and remarks it is believed that claims 2 - 6 and 8 are now in condition for allowance. Reconsideration of said claims by the Examiner is respectfully requested and the allowance thereof is courteously solicited.

CONDITIONAL PETITION FOR EXTENSION OF TIME

If any extension of time for this response is required, Applicants request that this be considered a petition therefor. Please charge the required petition fee to Deposit Account No. 14-1263.

ADDITIONAL FEE

Please charge any insufficiency of fee or credit any excess to Deposit Account No. 14-1263.

Respectfully submitted,
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